

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	8494	29/602.1,606,607,829,832.ccls.	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 08:42
S2	3956	336/200,212,223,232.ccls.	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 08:42
S3	682	205/119,122.ccls.	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 08:42
S4	2676	216/67.ccls.	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 08:42
S5	2	dip\$4 near (catalytic near metal)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 08:56
S6	79	dip\$4 with (catalytic near metal)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 08:46
S7	3	(catalytic near metal) with (dipole adj moment)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 08:46
S8	3	S6 and S7	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 08:50
S9	3	("5430613" "5781077" "5959846").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/08 08:47
S10	0	S9 and (catalytic near metal)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 09:08
S11	2	S8 and plasma	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 08:55
S12	0	dip\$4 near (tin near chlori\$2) near ((catalytic or palladium) near particle)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 09:11

EAST Search History

S13	0	(tin near chlori\$2) near ((catalytic or palladium) near particle)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 08:58
S14	8	(tin near chlori\$2) with ((catalytic or palladium) near particle)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 09:05
S15	2	NUYTKENS-PETER.in. or POPEKO-ILYA.in. or KULINETS-JOSEPH.in.	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 09:07
S16	18	NUYTKENS-PETER-r.in. or POPEKO-ILYA-e.in. or KULINETS-JOSEPH-m.in.	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/06/22 11:54
S17	6	S16 and (catalytic near metal)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 09:08
S18	14647	((catalytic or palladium or cobalt or ruthenium or platinum or ridium or osmium or nickel or iron) near particle)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 09:12
S19	0	(tin near chlori\$2) near ((catalytic or palladium or cobalt or ruthenium or platinum or ridium or osmium or nickel or iron) near particle)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 09:13
S20	0	dip\$4 near ((catalytic or palladium or cobalt or ruthenium or platinum or ridium or osmium or nickel or iron) near particle)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 09:14
S21	113	solution near ((catalytic or palladium or cobalt or ruthenium or platinum or ridium or osmium or nickel or iron) near particle)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 09:13
S22	59	dip\$4 with ((catalytic or palladium or cobalt or ruthenium or platinum or ridium or osmium or nickel or iron) near particle)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 09:26
S23	6	S21 and S22	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 09:14
S24	227368	metal\$3 near salt	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 09:24

EAST Search History

S25	10326	metal\$3 near salt near solution	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 09:15
S26	9	S22 and S25	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 09:15
S27	4	(US-5577906-\$ or US-4576689-\$ or US-5915953-\$ or US-3893949-\$). did.	USPAT	OR	ON	2005/12/08 09:21
S28	27502	electroless adj plat\$3	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 10:44
S29	166	S21 or S22	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 09:22
S30	29	S28 and S29	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 09:22
S31	12	S25 and S28 and S29	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 09:24
S32	673	(metal\$3 near salt) near (reduc\$3 adj agent)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 09:24
S33	1	S32 and S28 and S29	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 10:43
S34	6	dip\$4 with ((catalytic or palladium or cobalt or ruthenium or platinum or iridium or osmium or nickel or iron) near particle)	JPO; DERWENT	OR	ON	2005/12/08 09:26
S35	12617	induct\$3 near (core or device)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 10:44
S36	94	S35 and (electroless adj plat\$3)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 10:45

EAST Search History

S37	6	(induct\$3 near (core or device)) same (electroless adj plat\$3)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2005/12/08 10:45
S38	291	(dip\$4 or immers\$3) with (catalyti\$3 near metal)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/06/22 12:10
S39	489	(dip\$4 or immers\$3) with (metal near salt near solution)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/06/22 13:12
S40	27	(dip\$4 or immers\$3) with (metal near salt near solution) with (reduc\$3 near agent)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/06/22 11:57
S41	6	S38 and S40	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/06/22 11:57
S42	13	("20010002275" "20020163076" "3903590" "4783695" "4954811" "5161093" "5353498" "5373627" "5874770" "6034332" "6194291" "6194317" "6274821").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/22 12:03
S43	0	S38 and S42	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/22 12:03
S44	0	S39 and S42	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/22 12:04
S45	27239	electroless or (electro near less)	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/22 12:05
S46	18443	(electroless or (electro near less)) near plat\$3	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/22 12:05
S47	98	S39 and S46	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/22 12:05
S48	125	S38 and S46	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/22 12:05
S49	8	S47 and S48	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/22 12:05
S50	318	(dip\$4 or immers\$3) with (catalyti\$3 near (metal or particle))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/06/22 13:21

EAST Search History

S51	12	S39 and S50	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/06/22 12:56
S52	3	(("5430613") or ("5781077") or ("5959846")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/06/22 12:56
S53	6	S38 and S40	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/06/22 12:56
S54	0	S38 and S52	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/06/22 12:56
S55	0	S39 and S52	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/06/22 12:56
S56	5	(dip\$4 or immers\$3) with (metal near salt near solution) with plastic	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/06/22 13:15
S57	104	((metal near salt near solution) with reducing) same ((electroless or (electro near less)) near plat\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/06/22 13:17
S58	100	((metal near salt near solution) with (reducing near agent)) same ((electroless or (electro near less)) near plat\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/06/22 13:17
S59	78	((metal near salt near solution) with (reducing near agent)) with ((electroless or (electro near less)) near plat\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/06/22 13:22
S60	6	S50 and S59	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/06/22 13:18
S61	13	((metal near salt near solution) near (reducing near agent)) with ((electroless or (electro near less)) near plat\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/06/22 13:19
S62	6	(((metal near salt near solution) with (reducing near agent)) with ((electroless or (electro near less)) near plat\$3)) same ((dip\$4 or immers\$3) with (catalyti\$3 near (metal or particle)))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/06/22 13:22
S63	33	(((metal near salt near solution) with (reducing near agent)) with ((electroless or (electro near less)) near plat\$3)) same (catalyti\$3 near (metal or particle))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/06/22 13:23



Home | Login | Logout | Access Information | Alerts |
Welcome United States Patent and Trademark Office

Search Results

[BROWSE](#)[SEARCH](#)[IEEE Xplore Guide](#)

Results for "((((electroless plating) <and> (printed circuit board))<in>metadata)) <and> (pyr &...)"
Your search matched 2 of 1360403 documents.

[e-mail](#)

A maximum of 100 results are displayed, 25 to a page, sorted by **Relevance** in **Descending** order.

» Search Options

[View Session History](#)[New Search](#)

Modify Search

((((electroless plating) <and> (printed circuit board))<in>metadata)) <and> (pyr >= 19)

Check to search only within this results set

Display Format: Citation Citation & Abstract

» Key

IEEE JNL IEEE Journal or Magazine

IEE JNL IEE Journal or Magazine

IEEE CNF IEEE Conference Proceeding

IEE CNF IEE Conference Proceeding

IEEE STD IEEE Standard

[Select All](#) [Deselect All](#)

1. **Application of via post interconnection for build up printed circuit board**
Kobayashi, T.; Itaya, S.; Ikeda, K.; Kawasaki, J.; Honma, H.;
[IEMT/IMC Symposium, 2nd 1998](#)
15-17 April 1998 Page(s):312 - 315
Digital Object Identifier 10.1109/IEMTIM.1998.704666
[AbstractPlus](#) | Full Text: [PDF\(420 KB\)](#) IEEE CNF
[Rights and Permissions](#)

2. **Formation of Ni₃Sn₄ at the boundary between Sn-Pb soldering layers and coatings**
Maeda, A.; Umemura, T.; Qu, W.; Tomita, Y.; Abe, T.;
[Advanced Packaging Materials: Processes, Properties and Interfaces, 2000. Proceedings of the International Symposium on](#)
6-8 March 2000 Page(s):135 - 140
Digital Object Identifier 10.1109/ISAPM.2000.869257
[AbstractPlus](#) | Full Text: [PDF\(436 KB\)](#) IEEE CNF
[Rights and Permissions](#)

[Help](#) [Contact Us](#) [Privacy &](#)

© Copyright 2006 IEEE -

Indexed by
 Inspec